

Preliminary Technical Data Sheet

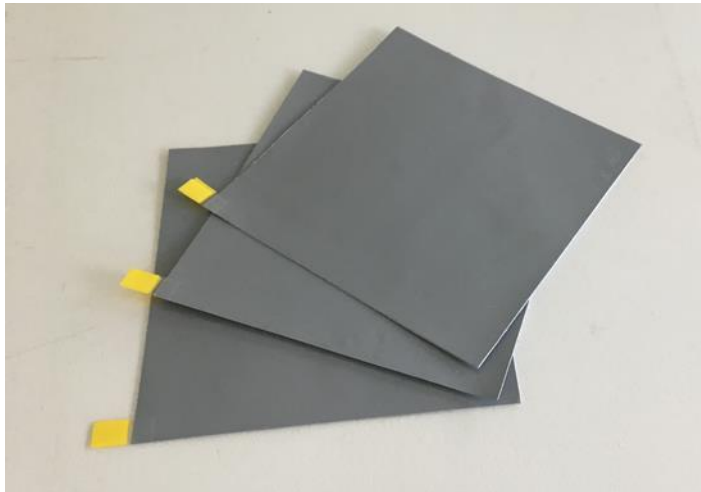
Phase Change Thermal Interface Material

PCM 21-780

Description

PCM 21-780, phase change interface thermal material, is designed to maximize heat sink performance and improve component reliability. It minimizes thermal resistance at interfaces, maintaining excellent performance when it fills interfacial gaps and voids.

At room temperature, PCM 21-780 is solid and easy to handle. This allows it to be consistently and cleanly applied as dry pad to heat sink or component surface. Upon reaching its softening temperature of 50~60 °C, PCM 21-780 begins to soften and flow, filling the microscopic irregularities of the component it comes into contact with. The result is an interface with minimal bond-line thickness and thermal contact resistance.



Benefits

- Low thermal resistance
- Phase change at 50~60°C
- Excellent interface wettability
- High reliability

Applications

CPUs (Notebooks, Desktops, Servers)

Chipsets

GPUs

ASIC Chips

Typical Properties

Properties		21-780	Test Method
Thermal	Thermal conductivity @80°C, 40psi (W/m-K)	6.0	ASTM D5470
	Thermal Resistance @80°C, 10psi (°C-cm ² /W)	0.26	ASTM D5470
	Thermal Resistance @80°C, 40psi (°C-cm ² /W)	0.06	
	Phase change softening temp. (°C)	50~60	DSC
	Continuous Use Temp. (°C)	-40~125	
Physical	Color	Grey	
	Standard Thickness (mm)	0.25~1.0	ASTM D374
	Density (g/cm ³)	2.76	ASTM D792

Ordering Information

